

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-11 (Cancelled)

12. (Currently Amended) An assembly comprising:

a connector with a dielectric body with first and second longitudinally opposed and laterally offset portions and an internal cavity, an offset electrically conductive path being disposed within the internal cavity and extending from the first portion of the dielectric body to the second portion of the dielectric body and including a compressible conductor disposed within the internal cavity in the second portion of the dielectric body;

a component adjacent the second portion of the body having a substantially flat mating portion in contact with and arranged substantially perpendicular to an end of the compressible conductor.

13. (Original) The assembly of Claim 12, wherein:

the compressible conductor comprises a compressible wire bundle.

14. (Original) The assembly of Claim 13, wherein:

the compressible conductor further comprises an electrically conductive plunger in electrical connection with the wire bundle.

15. (Original) The assembly of Claim 12, wherein:

the compressible conductor comprises a spring probe.

16. (Original) The assembly of Claim 12, wherein the connector has a tuned characteristic impedance.

17. (Original) The assembly of Claim 12, wherein:
the electrically conductive path includes a first conductor with a first end disposed in the internal cavity in the first portion of the body and a second end disposed in the internal cavity in the second portion of the body, the second end of the first conductor being in electrical contact with the compressible conductor.

18. (Original) The assembly of Claim 17, wherein:
the compressible conductor comprises a compressible wire bundle.

19. (Original) The assembly of Claim 18, wherein:
the compressible conductor further comprises an electrically conductive plunger in electrical connection with the wire bundle.

20. (Original) The assembly of Claim 17, wherein:
the compressible conductor comprises a spring probe.

21. (Original) The assembly of Claim 17, wherein the first conductor is a bent conductive pin.

22. (Original) The assembly of Claim 12, further comprising:
a connector housing.

23. (Original) The assembly of Claim 22, wherein the connector housing includes a first connector housing portion and a second connector housing portion.

24. (Original) The assembly of Claim 22, wherein the connector housing comprises metal.

25. (Currently Amended) A method for connecting a mating portion of a first component with a mating portion of a second component, comprising:

providing a connector with a dielectric body with first and second longitudinally opposed and laterally offset portions and an internal cavity, an offset electrically conductive path being disposed within the internal cavity and extending from the first portion of the dielectric body to the second portion of the dielectric body and including a compressible conductor disposed within the internal cavity in the second portion of the dielectric body;

positioning a first component with a first mating portion adjacent the first portion of the dielectric body such that a first end of the electrically conductive path is in electrical contact with the first mating portion; and

positioning a second component with a second mating portion adjacent the second portion of the body such that an end of the compressible conductor is in electrical contact with the second mating portion, wherein the second mating portion is substantially flat and arranged substantially perpendicular with the compressible conductor.

26. (Original) The method of Claim 25, wherein:

the compressible conductor comprises a compressible wire bundle.

27. (Original) The method of Claim 26, wherein:

the compressible conductor further comprises an electrically conductive plunger in electrical connection with the wire bundle.

28. (Original) The method of Claim 25, wherein:

the compressible conductor comprises a spring probe.

29. (Original) The method of Claim 25, wherein the connector has a tuned characteristic impedance.

30. (Original) The method of Claim 25, wherein:
the electrically conductive path includes a first conductor with a first end disposed in the internal cavity in the first portion of the body and a second end disposed in the internal cavity in the second portion of the body, the second end of the first conductor being in electrical contact with the compressible conductor.

31. (Original) The method of Claim 30, wherein:
the compressible conductor comprises a compressible wire bundle.

32. (Original) The method of Claim 31, wherein:
the compressible conductor further comprises an electrically conductive plunger in electrical connection with the wire bundle.

33. (Original) The method of Claim 30, wherein:
the compressible conductor comprises a spring probe.

34. (Original) The method of Claim 30, wherein the first conductor is a bent conductive pin.

35. (Original) The method of Claim 30, wherein the conductor has a tuned characteristic impedance.

36. (Original) The method of Claim 25 further comprising disposing the connector within a connector housing.

37. (Original) The method of Claim 36 wherein the connector housing includes a first connector housing portion and a second connector housing portion.

38. (Original) The method of Claim 36, wherein the connector housing comprises metal.

39. (Original) A connector providing an offset interconnect, comprising:
a dielectric body with first and second longitudinally opposed and laterally offset portions and an internal cavity;
an offset electrically conductive path disposed within the internal cavity, the offset electrically conductive path extending from the first portion of the dielectric body to the second portion of the dielectric body and including a first compressible conductor disposed within the internal cavity in the first portion of the dielectric body and a second compressible conductor disposed within the internal cavity in the second portion of the dielectric body.

Claims 40-42 (cancelled).

43. (New) A connector providing an offset interconnect, comprising:
a dielectric body with first and second longitudinally opposed and laterally offset portions and an internal cavity, wherein the first portion comprises a first opening and the second portion comprises a second opening;
an offset electrically conductive path disposed within the internal cavity, the offset electrically conductive path extending from the first portion of the dielectric body to the second portion of the dielectric body and including a first compressible conductor disposed at least partially within the internal cavity in the first portion of the dielectric body, wherein a portion of the first compressible conductor extends through the first opening.

44. (New) The connector of claim 43, further comprising:

a second compressible conductor disposed with in the internal cavity in the second portion, wherein a portion of the second compressible conductor extends through the second opening.

45. (New) The connector of Claim 44, wherein the first compressible conductor comprises a compressible wire bundle.

46. (New) The connector of Claim 45, wherein the first compressible conductor further comprises an electrically conductive plunger in electrical connection with the wire bundle.

47. (New) The connector of claim 46, wherein a portion of the electrically conductive plunger extends through the first opening.

48. (New) The connector of Claim 47, wherein the compressible conductor comprises a spring and a plunger, and wherein a portion of the plunger extends through the first opening.

49. (New) The connector of Claim 48, wherein the connector has a tuned characteristic impedance.

50. (New) A stacked circuit board assembly comprising:

a first circuit board, comprising at least a first mating portion;

a second circuit board, comprising at least a second mating portion, wherein the first mating portion is laterally offset from the second mating portion when the first and second circuit boards are in respective assembled positions;

a connector for electrically connecting the first and second mating portions, wherein the connector comprises an offset electrically conductive path from the first mating portion to the second mating portion, wherein the electrically conductive path comprises a first compressible conductor in electrical contact with the first mating portion and a second compressible conductor in electrical contact with the second mating portion.

51. (New) The stacked circuit board assembly of Claim 50, wherein the connector comprises a connector body portion comprising a first connector body portion and a second connector body portion, wherein the first compressible conductor is at least partially within the first connector body portion and the second compressible conductor is at least partially within the second connector body portion.

52. (New) The stacked circuit board assembly of claim 51, wherein the connector body comprises a dielectric.

53. (New) The stacked circuit board assembly of claim 51, further comprising a connector housing arranged between the first circuit board and the second circuit board, the connector housing comprising a first connector housing portion for housing at least the first connector body portion and a second connector housing portion for housing at least the second connector housing portion.

54. (New) The stacked circuit board assembly of claim 53, wherein the connector housing comprises metal.